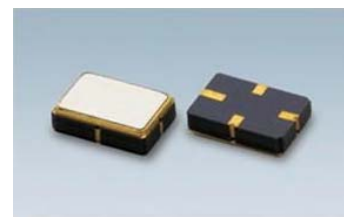


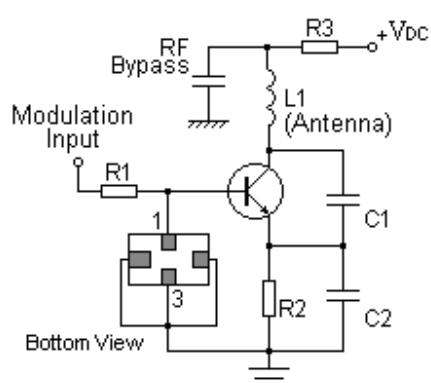
Features

- Ceramic Package for Surface Mounted Technology (SMT)
- RoHS compatible
- Package size 5.00x3.50x1.50mm³
- Package Code QCC4A

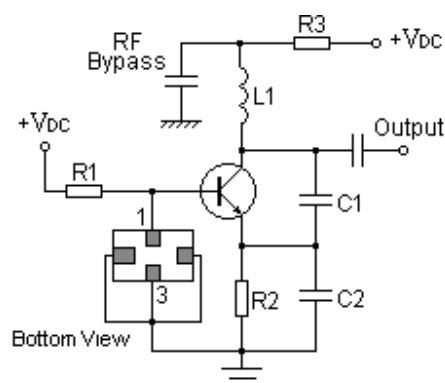


Application

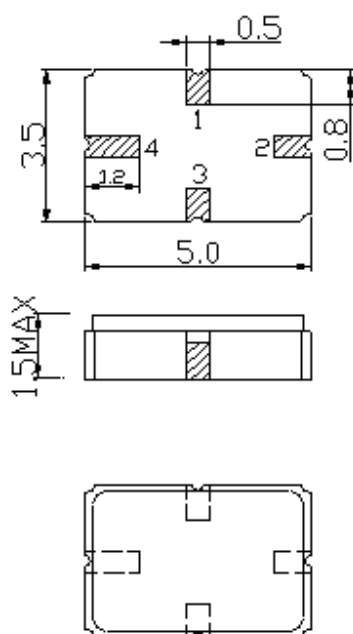
Typical Low-Power Transmitter Application



Typical Local Oscillator Application



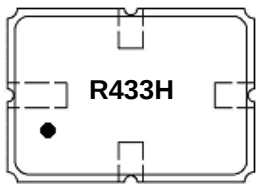
Package Dimensions (QCC4A)



Pin Configuration

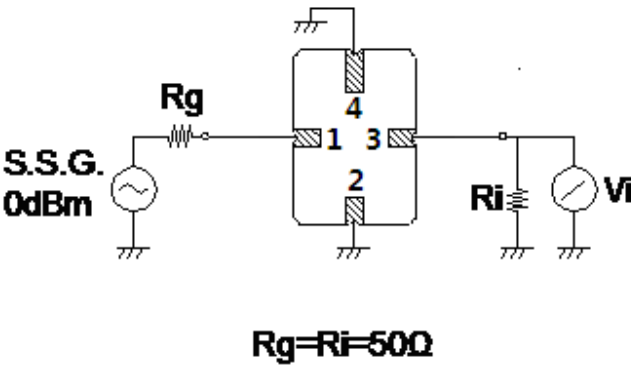
Pin No.	Description
1	Input
3	Output
2,4	Ground

Marking Description

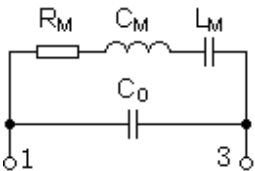


●	Pin 4
R	Manufacturer& SAW Resonator
433H	Part Number

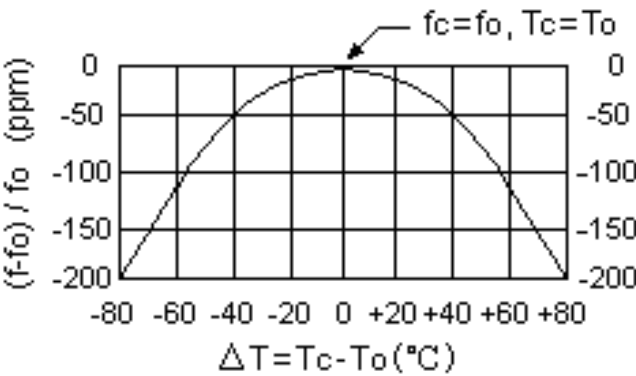
Test Circuit



Equivalent LC Model



Temperature Characteristics



The curve shown above accounts for resonator contribution only and does not include LC component temperature contributions.

Performance**Maximum Rating**

Item		Value	Unit
DC Voltage	V_{DC}	± 30	V
Operation Temperature	T	-40 ~ +85	°C
Storage Temperature	T_{stg}	-55 ~ +125	°C
RF Power Dissipation	P	10	dBm

Electronic Characteristics

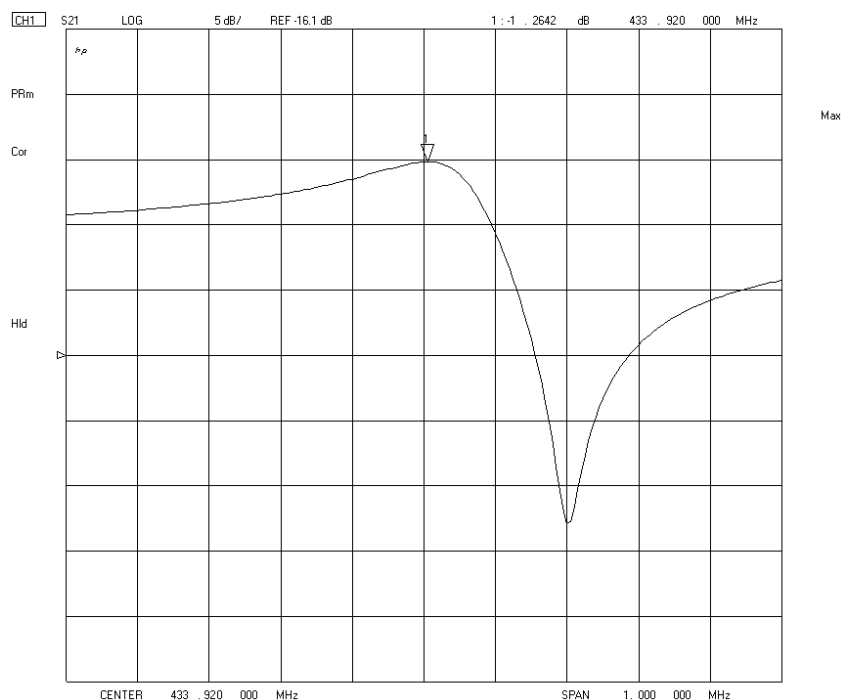
Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

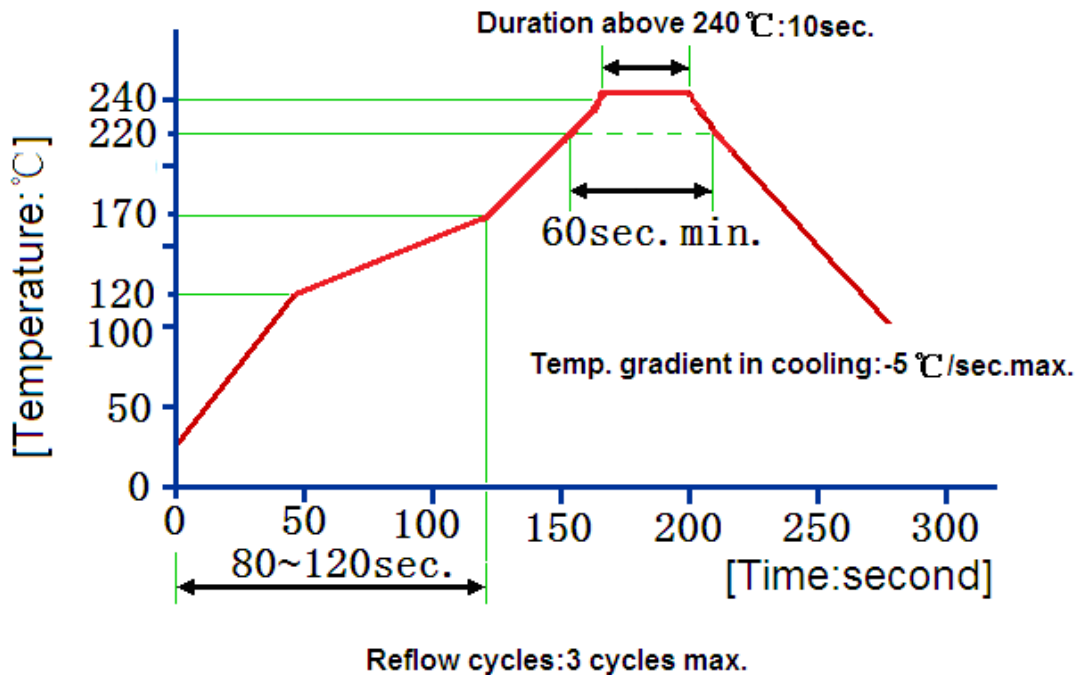
Item			Minimum	Typical	Maximum	Unit
Center Frequency	Absolute Frequency	f_c		433.92		MHz
	Tolerance from 433.92MHz	Δf_c		± 75		KHz
Insertion Loss(min)		IL		1.3	1.8	dB
Quality Factor	Unloaded Q	Q_U		15174		
	50 Ω Loaded Q	Q_L		1771		
Temperature Stability	Turnover Temperature	T_0	25	40	55	°C
	Turnover Frequency	f_0		f_c		
	Frequency Temperature Coefficient	FTC		0.032		ppm/°C
Frequency Aging	Absolute Value during the First Year	$ f_A $		≤ 10		ppm/yr
DC Insulation Resistance between Any Two Pins			1.0			M Ω
RF Equivalent RLC Model	Motional Resistance	R_M		13.0	22.0	Ω
	Motional Inductance	L_M		73.6		μH
	Motional Capacitance	C_M		1.83		fF
	Static Capacitance	C_0	2.1	2.4	2.7	pF

Frequency Characteristics



Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition
1	Temperature Storage	(1) Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h} \pm 0.5\text{h}$ (2) Temperature: $-55^{\circ}\text{C} \pm 3^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h} \pm 0.5\text{h}$
2	Humidity Test	Conditions: $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 90~95% RH Duration: 250h
3	Thermal Shock	Heat cycle conditions: $\text{TA} = -55^{\circ}\text{C} \pm 3^{\circ}\text{C}$, $\text{TB} = 85^{\circ}\text{C} \pm 2^{\circ}\text{C}$, $t_1 = t_2 = 30\text{min}$, Switch time: $\leq 3\text{min}$, Cycle time: 100 times, Recovery time: $2\text{h} \pm 0.5\text{h}$.
4	Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude: 1.5mm Directions: X,Y and Z Duration: 2h
5	Drop Test	Cycle time: 10 times Height: 1.0m
6	Solder Ability Test	Temperature: $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5
7	Resistance to Soldering Heat	(1) Thickness of PCB: 1mm , Solder condition: $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$, Duration: $10 \pm 1\text{s}$ (2) Temperature of Soldering Iron: $350^{\circ}\text{C} \pm 10^{\circ}\text{C}$, Duration: 3~4s , Recovery time : $2 \pm 0.5\text{h}$

Recommended Reflow Soldering Diagram**Notes**

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.